

<b>L Number</b>	<b>Hits</b>	<b>Search Text</b>	<b>DB</b>	<b>Time stamp</b>
<b>1</b>	<b>0</b>	<b>microcircuit and stacked and encapsulant and encasing and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:16</b>
<b>2</b>	<b>0</b>	<b>microcircuit and stacked and encapsulant and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:17</b>
<b>3</b>	<b>0</b>	<b>microcircuit and PEM and encapsulant and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:17</b>
<b>4</b>	<b>0</b>	<b>PEM and encapsulant and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:17</b>
<b>5</b>	<b>0</b>	<b>PEM and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:17</b>
<b>6</b>	<b>2601</b>	<b>PEM</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:17</b>
<b>7</b>	<b>80</b>	<b>( PEM ) and encapsulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:18</b>
<b>8</b>	<b>29</b>	<b>( PEM ) and encapsulation and removing</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:18</b>
<b>9</b>	<b>394917</b>	<b>( PEM ) and removing insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:20</b>
<b>10</b>	<b>0</b>	<b>( PEM ) and removing near insulation</b>	<b>USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB</b>	<b>2003/03/12 12:20</b>

11	0	( PEM ) and removing near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:21
12	2	( PEM ) and removing same encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:30
13	0	20020119605.URPN.	USPAT	2003/03/12 12:22
14	21	("4017495"   "4118861"   "4490496"   "4729062"   "4826756"   "4830922"   "4902769"   "4920639"   "4991286"   "5274913"   "5381304"   "5405807"   "5434751"   "5512613"   "5560934"   "5600181"   "5641546"   "5685071"   "5828126"   "5858943"   "6111323").PN.	USPAT	2003/03/12 12:22
15	41	("3801880"   "3864426"   "4012832"   "4370292"   "4529755"   "4604444"   "4626556"   "4632798"   "4663190"   "4729062"   "4738892"   "4983683"   "4985751"   "5037779"   "5043211"   "5061657"   "5064895"   "5072874"   "5120678"   "5128204"   "5140068"   "5160786"   "5199163"   "5250848"   "5264520"   "5274913"   "5286572"   "5298548"   "5300625"   "5313365"   "5326413"   "5371328"   "5381304"   "5434751"   "5457149"   "5460767"   "5471096"   "5474620"   "5498689"   "5821456"   "5863664").PN.	USPAT	2003/03/12 12:24
16	0	( PEM ) and removing and grinding near encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:31
17	0	( PEM ) and removing and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:32
18	6	removing and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:33
19	1	IC and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:36

20	0	8153696.URPN.	USPAT	2003/03/12 12:34
21	1	1996-331608.NRAN.	DERWENT	2003/03/12 12:34
22	552166	29/\$.ccls. grinding near encapsulant or insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:36
23	166292	29/\$.ccls. grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:37
24	2	29/\$.ccls. and grinding near (encapsulant or insulation)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:37
25	0	"Albert et al".inv.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:38
26	28	29/840.ccls. and microcircuit	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:39
27	3	29/840.ccls. and microcircuit and encapsulant	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:42
28	0	20020126459.URPN.	USPAT	2003/03/12 12:42
29	2	"Stackable microcircuit layer "	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:43
30	1	"Stackable microcircuit " and 174/52.2.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:43
31	4077	"Stackable microcircuit layer "and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:44

Class + Sub

32	0	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and grinding and removing and encasing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
33	1	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and grinding and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
34	1	"Stackable microcircuit layer" and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:45
35	23	microcircuit and (361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 12:48
36	4	(361/743;29/830 ;29/840 ;29/841 ;361/735 ;361/746).ccls. and encapsulant near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:07
37	17	("3903590"   "4466181"   "4783695"   "4835704"   "4878991"   "4933042"   "5019946"   "5048179"   "5091769"   "5108825"   "5139969"   "5144747"   "5151776"   "5154793"   "5155068"   "5161093"   "5255431").PN.	USPAT	2003/03/12 12:52
38	8	("3702464"   "4532419"   "4603249"   "4725924"   "4774633"   "4803542"   "4822989"   "4931853").PN.	USPAT	2003/03/12 13:03
39	10	("5207864"   "5386624"   "5406025"   "5483421"   "5638597"   "5739053"   "5785234"   "5813115"   "5816478"   "5873161").PN.	USPAT	2003/03/12 13:05
40	6	("3676745"   "5323295"   "5365403"   "5367439"   "5467251"   "5644103").PN.	USPAT	2003/03/12 13:06
41	60	encapsulant near removal	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:10
42	0	20010039120.URPN.	USPAT	2003/03/12 13:08
43	14	encapsulant near remove and pad and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:13

44	15	("4281031"   "4344809"   "4359360"   "4826556"   "5252179"   "5254237"   "5271798"   "5321222"   "5350737"   "5521360"   "5552112"   "5648038"   "5766496"   "6011249"   "6211499").PN.	USPAT	2003/03/12 13:12
45	4	("3469053"   "5268548"   "5644837"   "5725762").PN.	USPAT	2003/03/12 13:13
46	27	encapsulant and encasing and removing and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT	2003/03/12 13:19
47	19	("4143456"   "4264917"   "4300153"   "4358552"   "4507675"   "4642671"   "4931852"   "4961107"   "5101465"   "5173764"   "5194930"   "5379186"   "5434105"   "5436203"   "5450283"   "5488254"   "5489538"   "5489801"   "5866953").PN.	USPAT	2003/03/12 13:15
48	0	encapsulant and encasing near removing and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:19
49	0	encapsulant and encasing near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:19
50	79	encapsulant near removing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:26
51	11	("4460537"   "4615857"   "4910581"   "5417826"   "5434750"   "5542171"   "5557150"   "5635671"   "5656549"   "5780933"   "5963792").PN.	USPAT	2003/03/12 13:24
52	14	("4460537"   "4615857"   "4784974"   "4910581"   "5417826"   "5434750"   "5542171"   "5557150"   "5620928"   "5625235"   "5635671"   "5656549"   "5708567"   "5756380").PN.	USPAT	2003/03/12 13:25
53	0	"removing said encapsulant"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:30
54	0	encapsulant near grinding and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:31

55	4103	grinding and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:32
56	10	removing and grinding and encapsulant near material and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:35
57	0	20030006494.URPN.	USPAT	2003/03/12 13:34
58	15	grinding and encapsulant near material and semiconductor near device	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:35
59	33	grinding and encapsulant near material and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/12 13:36
60	8	("5471087"   "5773323"   "5855727"   "5863810"   "5897338"   "5932061"   "6069392"   "6136212").PN.	USPAT	2003/03/12 13:39
61	23	("H001379"   "3482419"   "3627901"   "3762039"   "3969813"   "4089704"   "4359360"   "4384917"   "4474621"   "4567006"   "4691225"   "4768286"   "4914813"   "4980019"   "5041396"   "5138430"   "5149662"   "5155068"   "5180093"   "5252179"   "5398926"   "5406117"   "5424254").PN.	USPAT	2003/03/12 13:46
62	19	5424254.URPN.	USPAT	2003/03/12 13:49